

## **LISTING OF THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

### **Claims 1-8 (Canceled)**

### **Claim 9 (Previously Presented)**

A substrate treatment method for treating a substrate by supplying a treatment liquid to the substrate while rotating the substrate, the method comprising the steps of:

performing a first substrate rotation process for rotating the substrate while clamping the substrate by a first clamping member set including at least two clamping members,

performing a second substrate rotation process after the first substrate rotation step for rotating the substrate while clamping the substrate by the first clamping member set and a second clamping member set provided separately from the first clamping member set and including at least two clamping members, and

performing a third substrate rotation process after the second substrate rotation step by unclamping the substrate from the first clamping member set for rotating the substrate while clamping the substrate by the second clamping member set,

wherein the first clamping member set includes three clamping members each having a first abutment portion and a second abutment portion which are selectively brought into abutment against the substrate, and the second clamping member set includes three clamping members each having a third abutment portion which is brought

into abutment against the substrate,

wherein the first substrate rotation step comprises the step of bringing the first abutment portions of the three clamping members of the first clamping member set into abutment against the substrate for clamping the substrate,

wherein the second substrate rotation step comprises the step of bringing the third abutment portions of the three clamping members of the second clamping member set into abutment against the substrate with the first abutment portions of the three clamping members of the first clamping member set kept in abutment against the substrate,

wherein the third substrate rotation step comprises the step of retracting the first abutment portions of the three clamping members of the first clamping member set from the substrate,

the method further comprising the steps of:

performing a fourth substrate rotation process after the third substrate rotation step by bringing the second abutment portions of the three clamping members of the first clamping member set into abutment against the substrate with the third abutment portions of the three clamping members of the second clamping member set kept in abutment against the substrate for rotating the substrate while clamping the substrate by the first and second clamping member sets, and

performing a fifth substrate rotation process after the fourth substrate rotation step by retracting the third abutment portions of the three clamping members of the second clamping member set from the substrate to unclamp the substrate from the second clamping member set for rotating the substrate while clamping the substrate by the first

substrate clamping member set.

**Claim 10 (Previously Presented)**

A substrate treatment method as set forth in claim 9,  
wherein the three clamping members of the second clamping member set each have the third abutment portion and a fourth abutment portion which are selectively brought into abutment against the substrate,

the method further comprising the steps of:

performing a sixth substrate rotation process after the fifth substrate rotation step by bringing the fourth abutment portions of the three clamping members of the second clamping member set into abutment against the substrate with the second abutment portions of the three clamping members of the first clamping member set kept in abutment against the substrate for rotating the substrate while clamping the substrate by the first and second clamping member sets, and

performing a seventh substrate rotation process after the sixth substrate rotation step by retracting the second abutment portions of the three clamping members of the first clamping member set from the substrate to unclamp the substrate from the first clamping member set for rotating the substrate while clamping the substrate by the second clamping member set.

**Claim 11 (Original)**

A substrate treatment method as set forth in claim 9, further comprising the step

of supplying the treatment liquid to a surface of the substrate being rotated at least in the first substrate rotation step, the third substrate rotation step and the fifth substrate rotation step.

**Claim 12 (Original)**

A substrate treatment method as set forth in claim 10, further comprising the step of supplying the treatment liquid to a surface of the substrate being rotated at least in the first substrate rotation step, the third substrate rotation step, the fifth substrate rotation step and the seventh substrate rotation step.

**Claim 13 (Original)**

A substrate treatment method as set forth in claim 11, wherein the treatment liquid supply step comprises the step of supplying an etching liquid for etching away an unnecessary substance from a peripheral edge portion of the substrate.

**Claim 14 (Original)**

A substrate treatment method as set forth in claim 12, wherein the treatment liquid supply step comprises the step of supplying an etching liquid for etching away an unnecessary substance from a peripheral edge portion of the substrate.

**Claim 15 (Original)**

A substrate treatment method as set forth in claim 9, further comprising the step

of supplying the treatment liquid to the substrate prior to the first substrate rotation step,  
wherein the treatment liquid is not supplied to the substrate during any of the first  
to fifth substrate rotation steps, but a drying process is performed by spinning off the  
treatment liquid by the rotation of the substrate.

**Claim 16 (Original)**

A substrate treatment method as set forth in claim 10, further comprising the step  
of supplying the treatment liquid to the substrate prior to the first substrate rotation step,  
wherein the treatment liquid is not supplied to the substrate during any of the first  
to seventh substrate rotation steps, but a drying process is performed by spinning off the  
treatment liquid by the rotation of the substrate.

**Claims 17-67 (Canceled)**